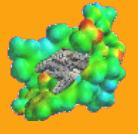




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HELSINGFORS UNIVERSITET
UNIVERSITY OF HELSINKI



CMS



HIP

Dislocation nucleation on near surface void under tensile stress in Cu

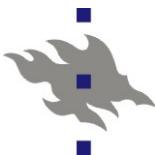
Aarne Pohjonen,

Flyura Djurabekova,
Kai Nordlund

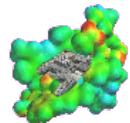
*Helsinki Institute of Physics and
Department of Physics
University of Helsinki
Finland*

Steve Fitzgerald

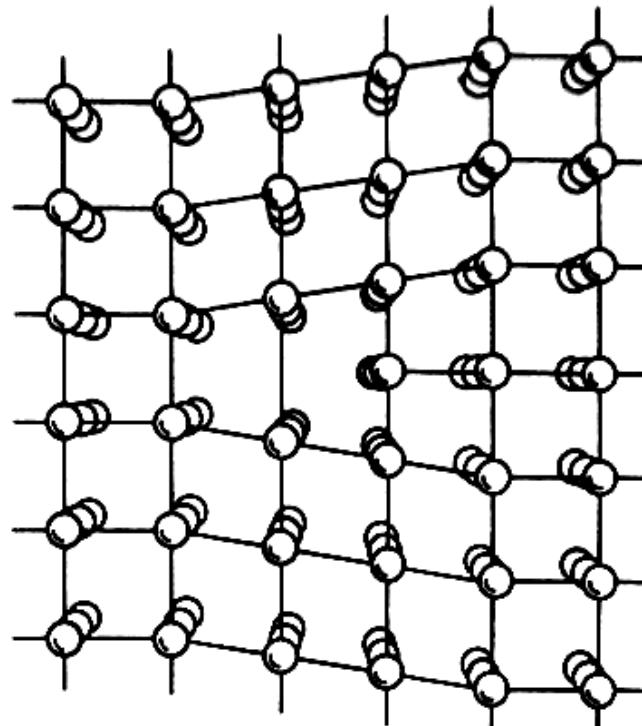
*Theory and Modelling
Culham Centre for Fusion Energy
UK*



Dislocations



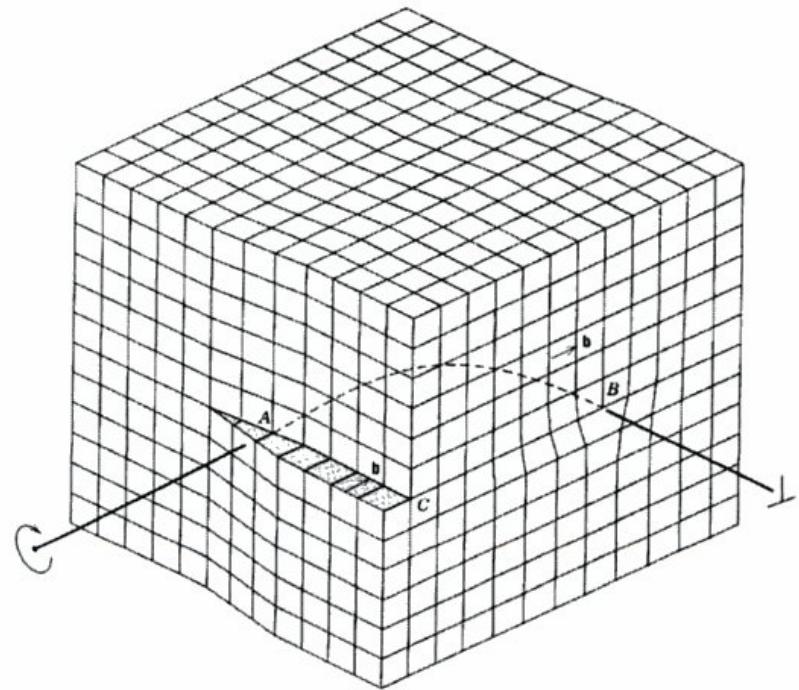
Edge dislocation
in simple cubic lattice



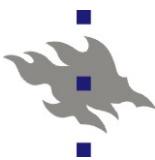
Theory of Dislocations, Hirth, Lothe, 1982



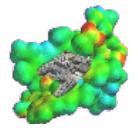
Mixed screw-edge
dislocation



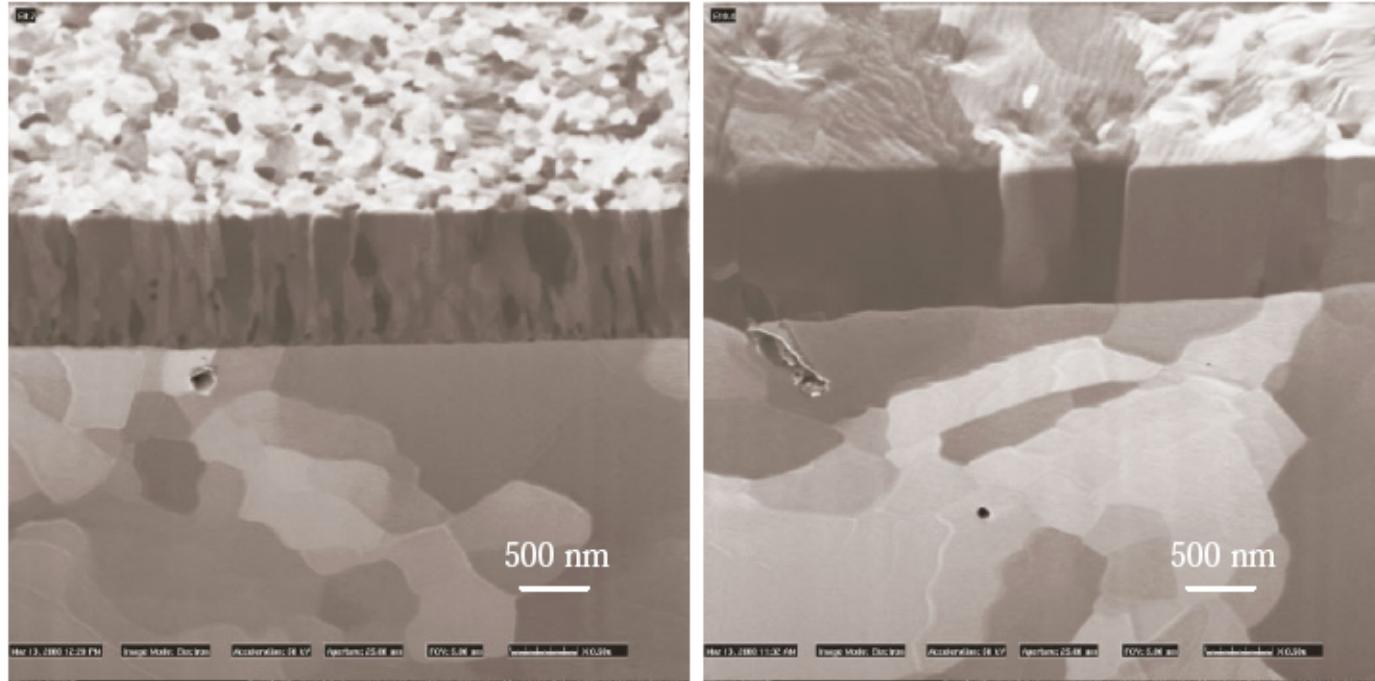
Materials Science and Engineering, Callister, 2000



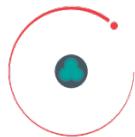
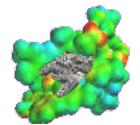
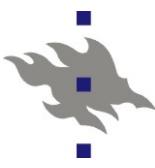
Voids



Voids are observed in cavities

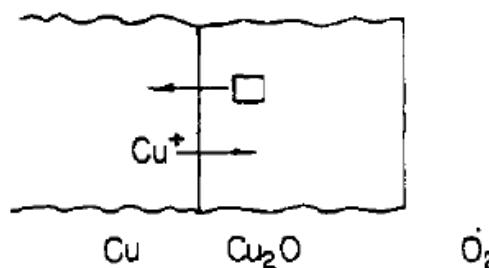
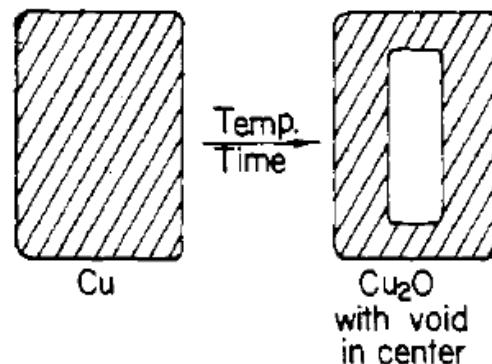


Cross sectional FIB images of niobium films on
oxidised (left) and oxide-free (right) copper substrates



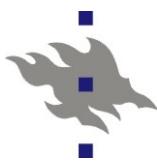
Voids

Possible near surface void formation mechanism:
Kirkendall effect

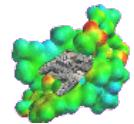


Copper oxidation and void formation.

*Void Formation Failure Mechanisms in
Integrated Circuits*, Selikson, 1969



Simulations



1. Relax the system
for 20 ps, no force



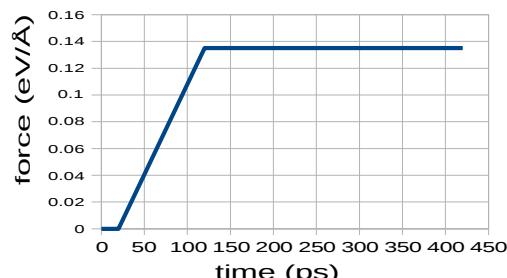
2. "Ramp up" the
force in 20...120 ps

3. Continue with

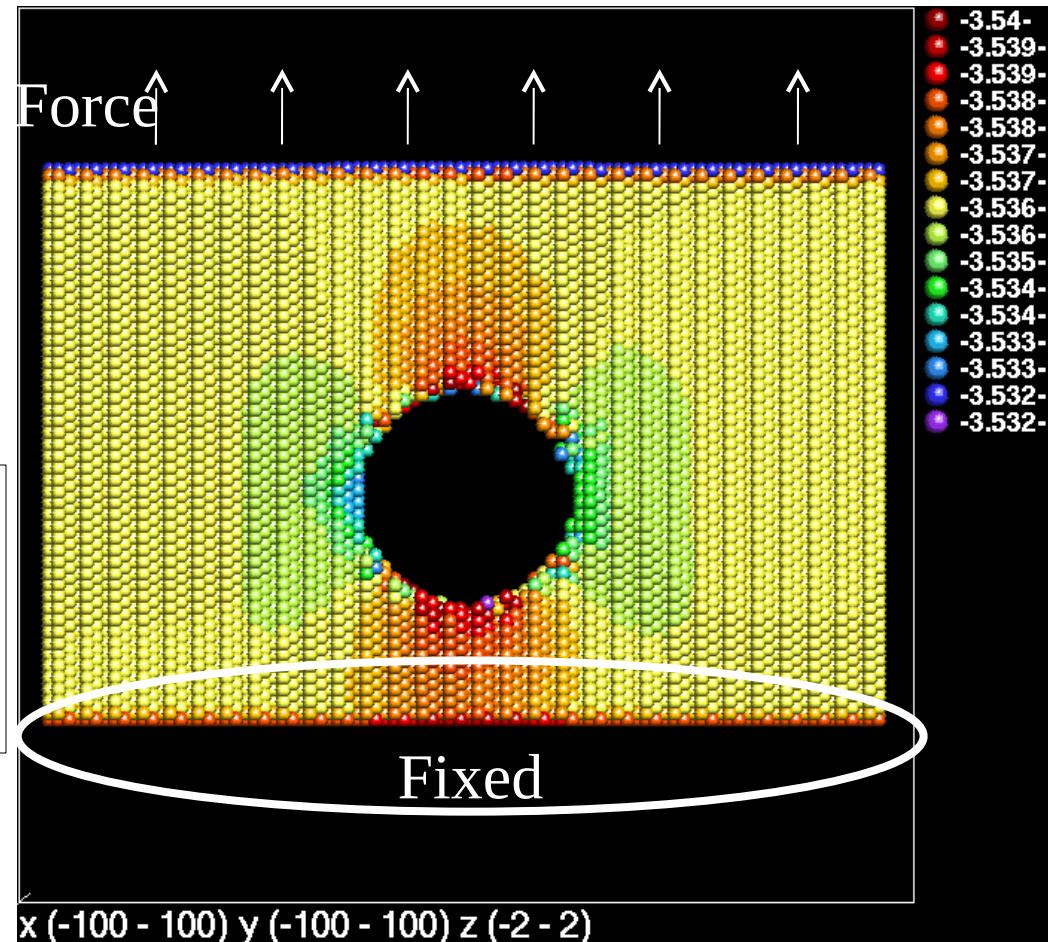
timescale $\Delta t = 300$ ps

force/atom $F = 0.135 \text{ eV}/\text{\AA}$

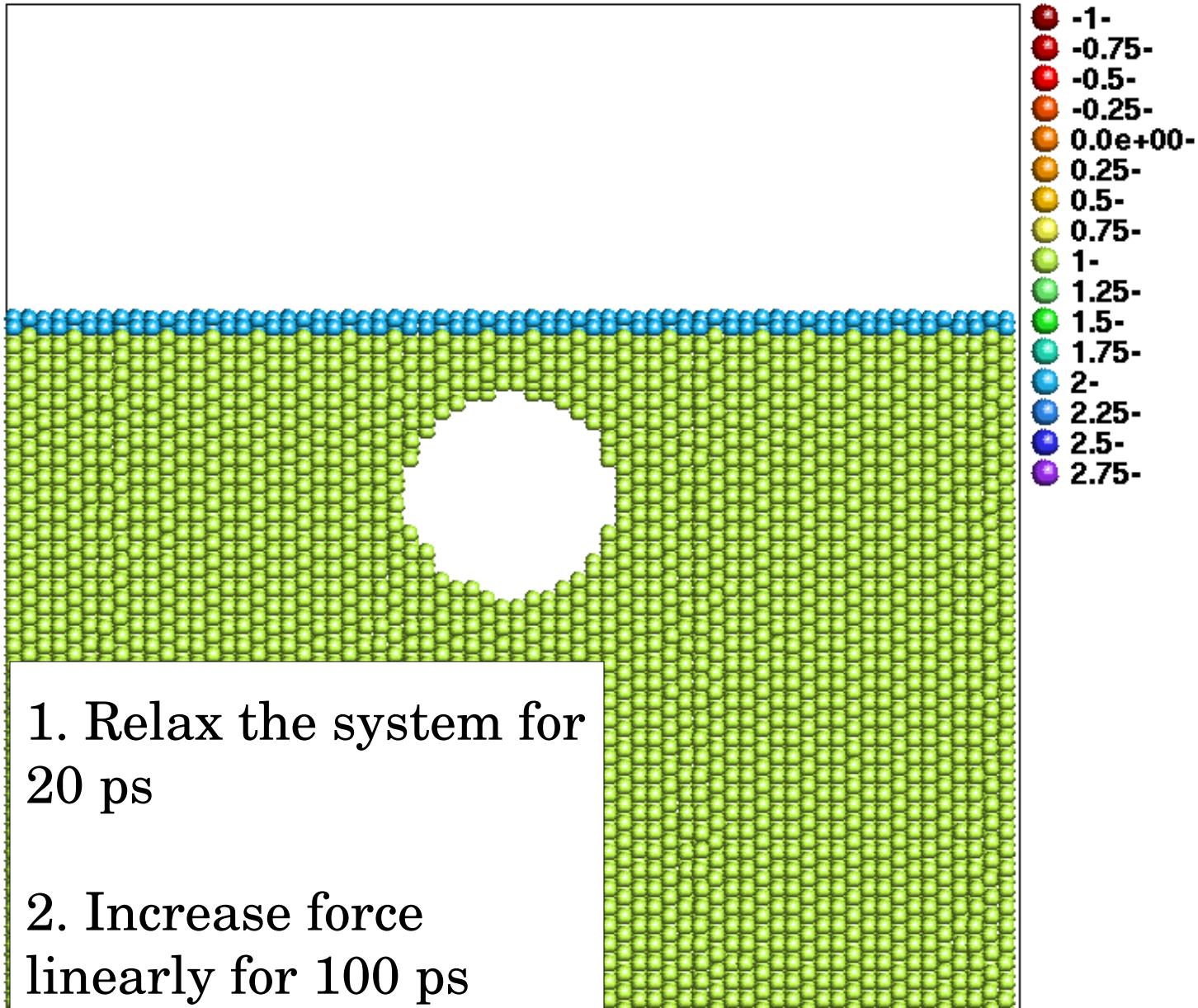
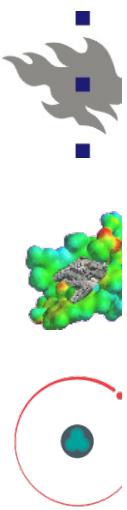
temperature $T = 600 \text{ K}$



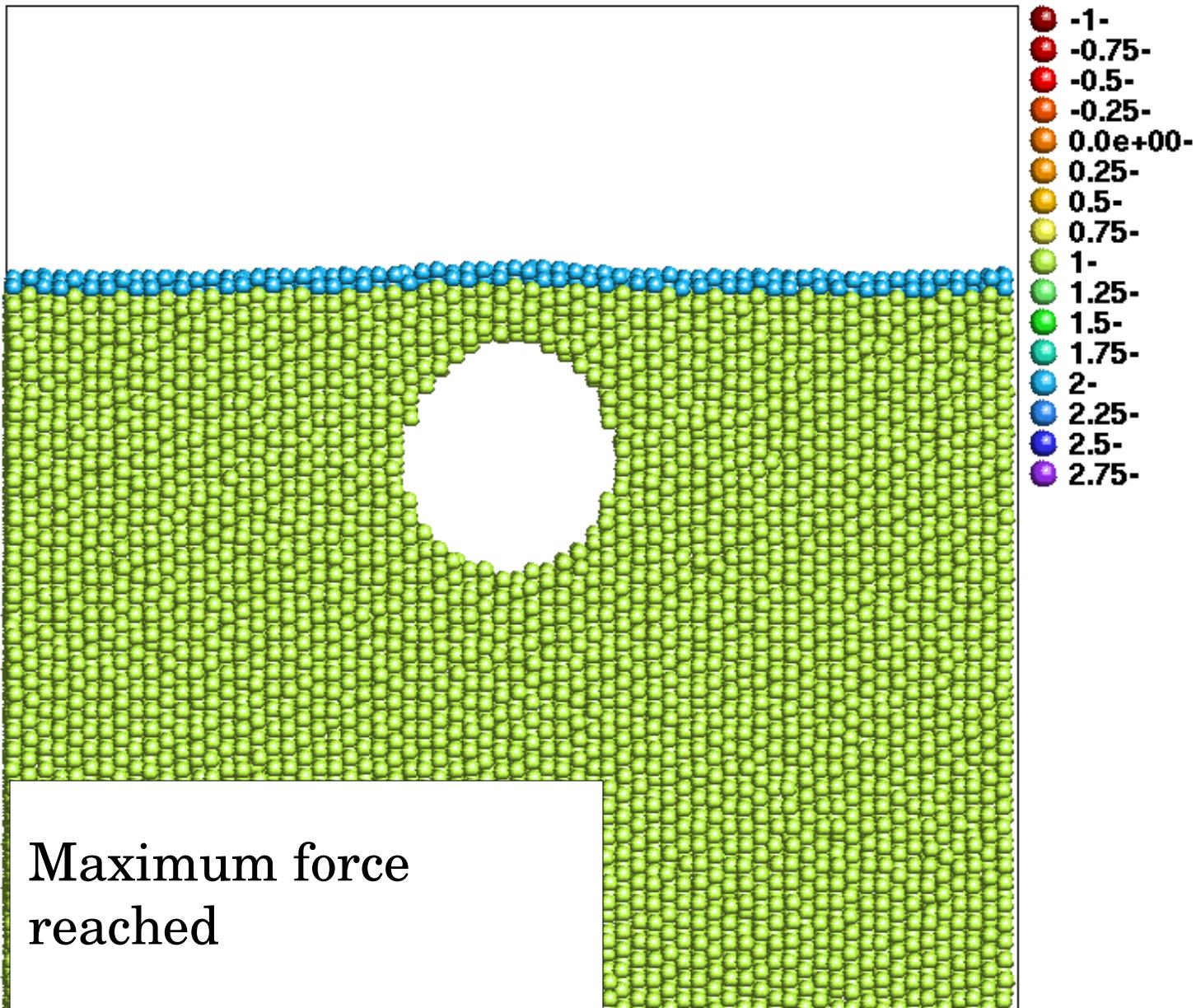
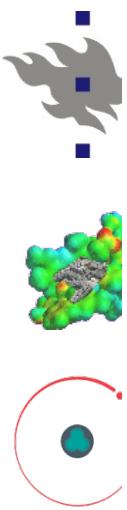
1ki

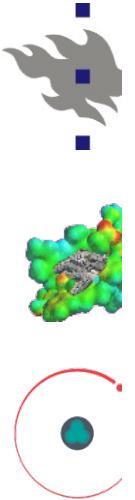


time 4.06 fs

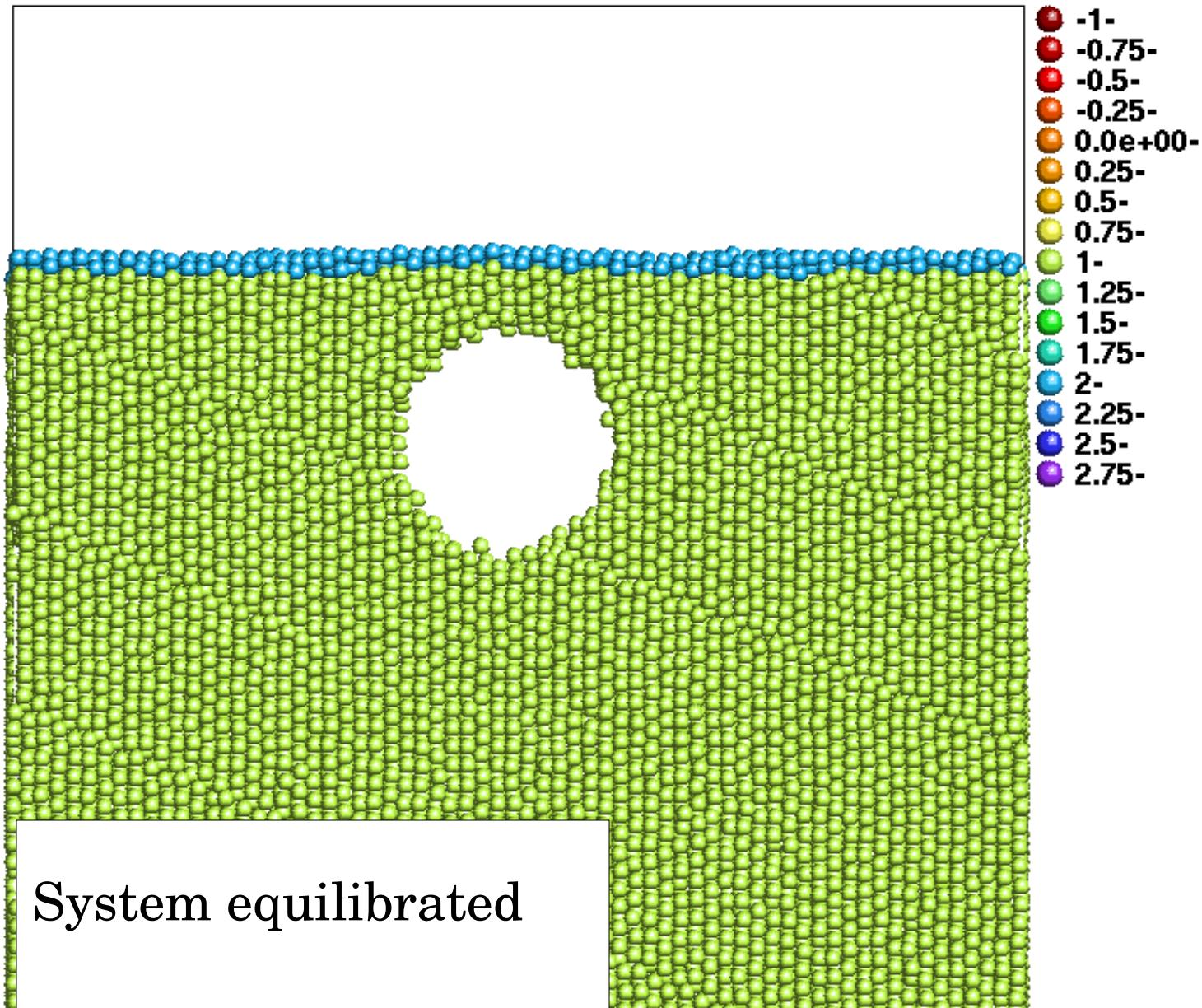


time 1.2e+05 fs



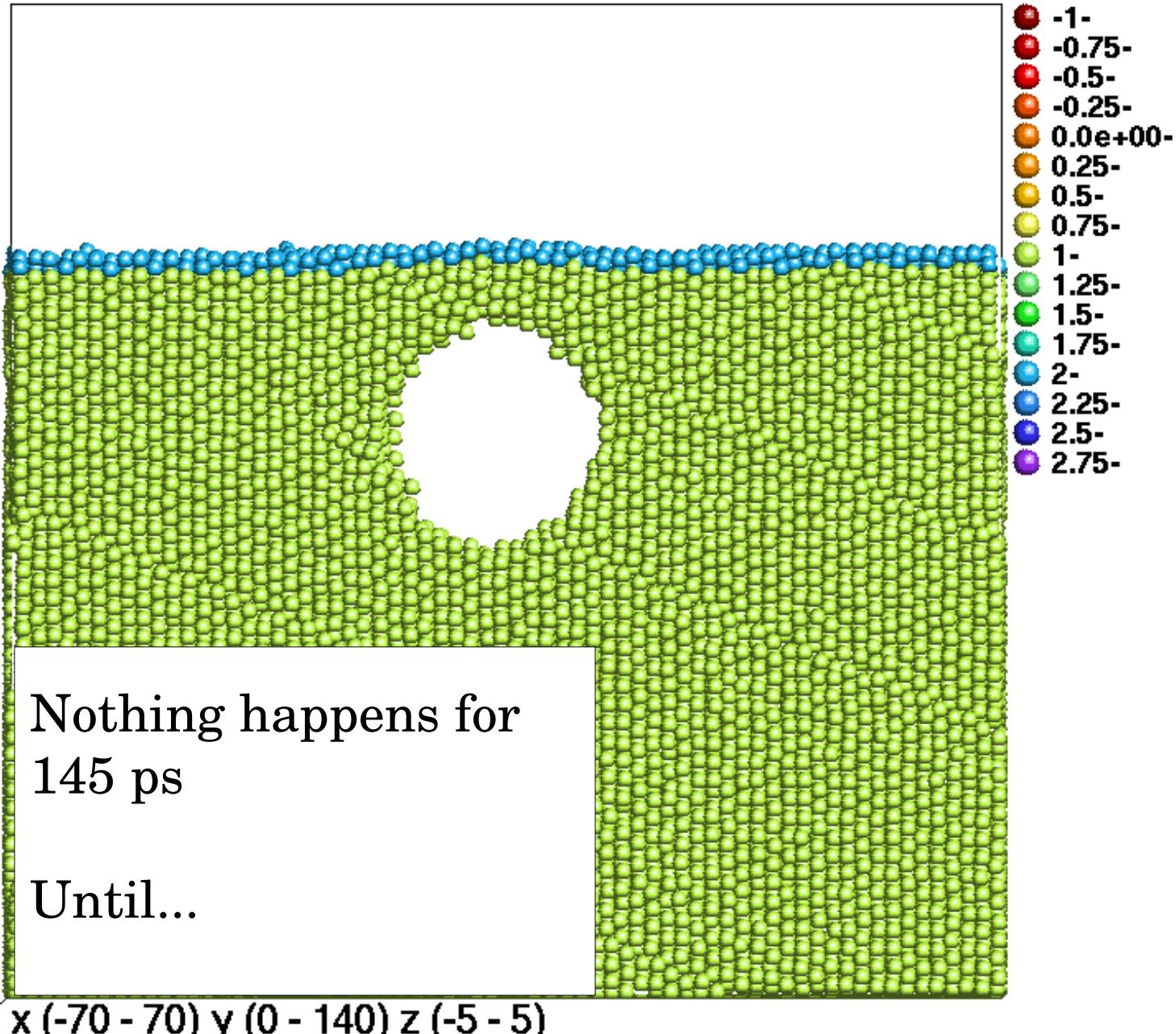
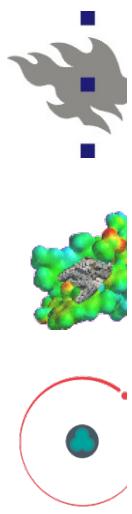


time 1.7e+05 fs

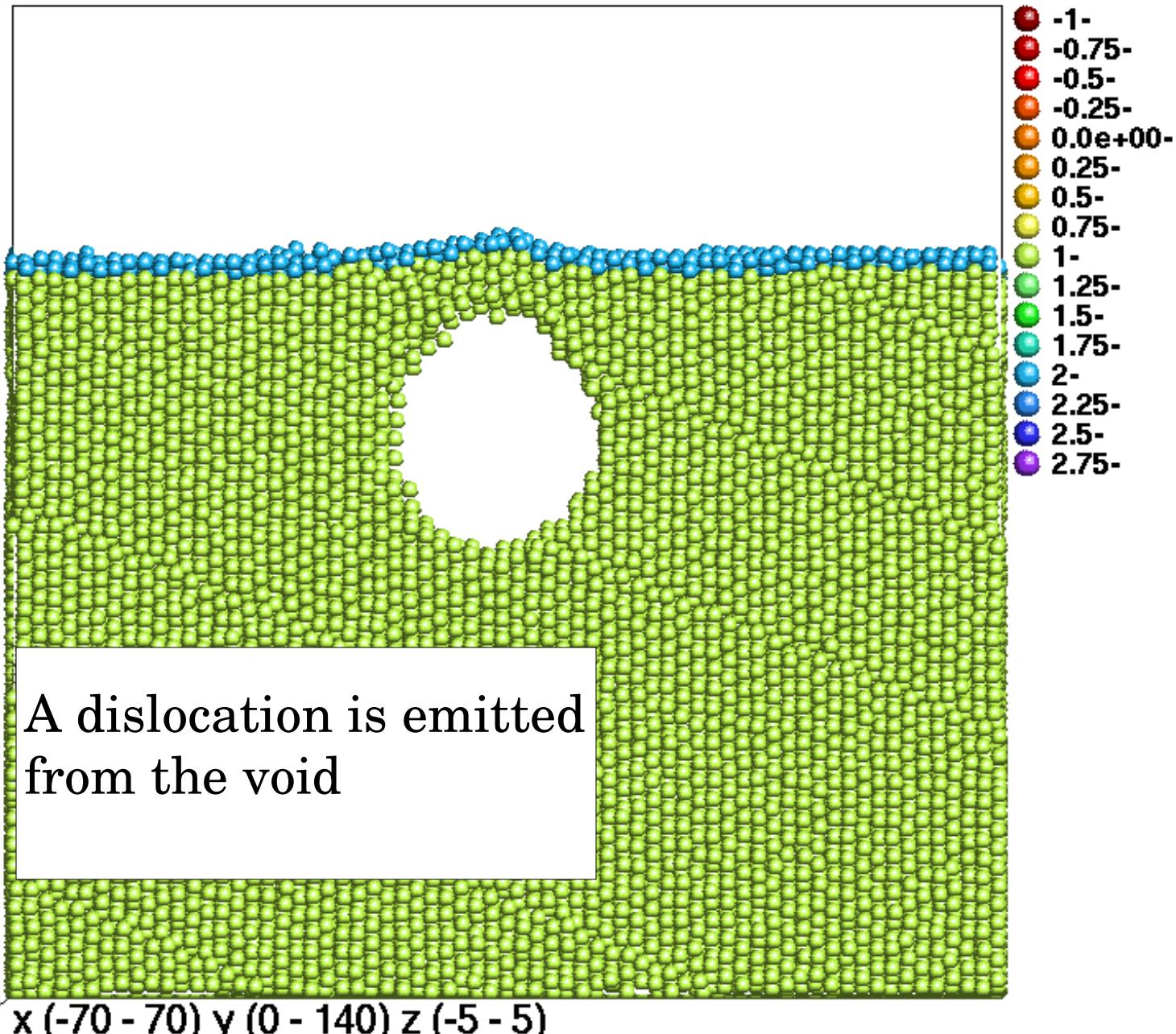
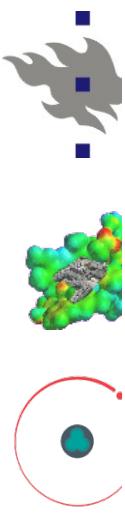


Aarne ↵ x (-70 - 70) y (0 - 140) z (-5 - 5)

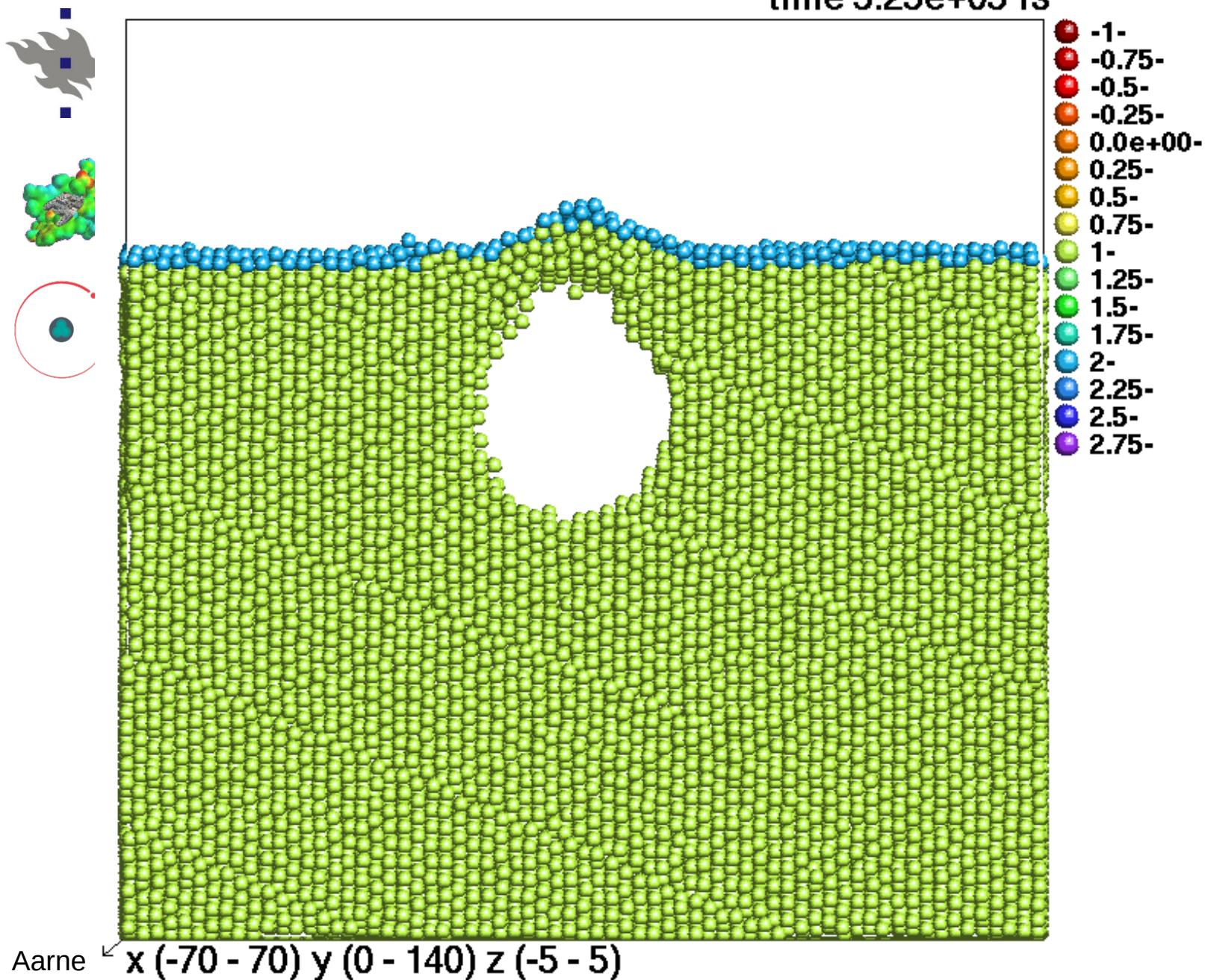
time 3.15e+05 fs



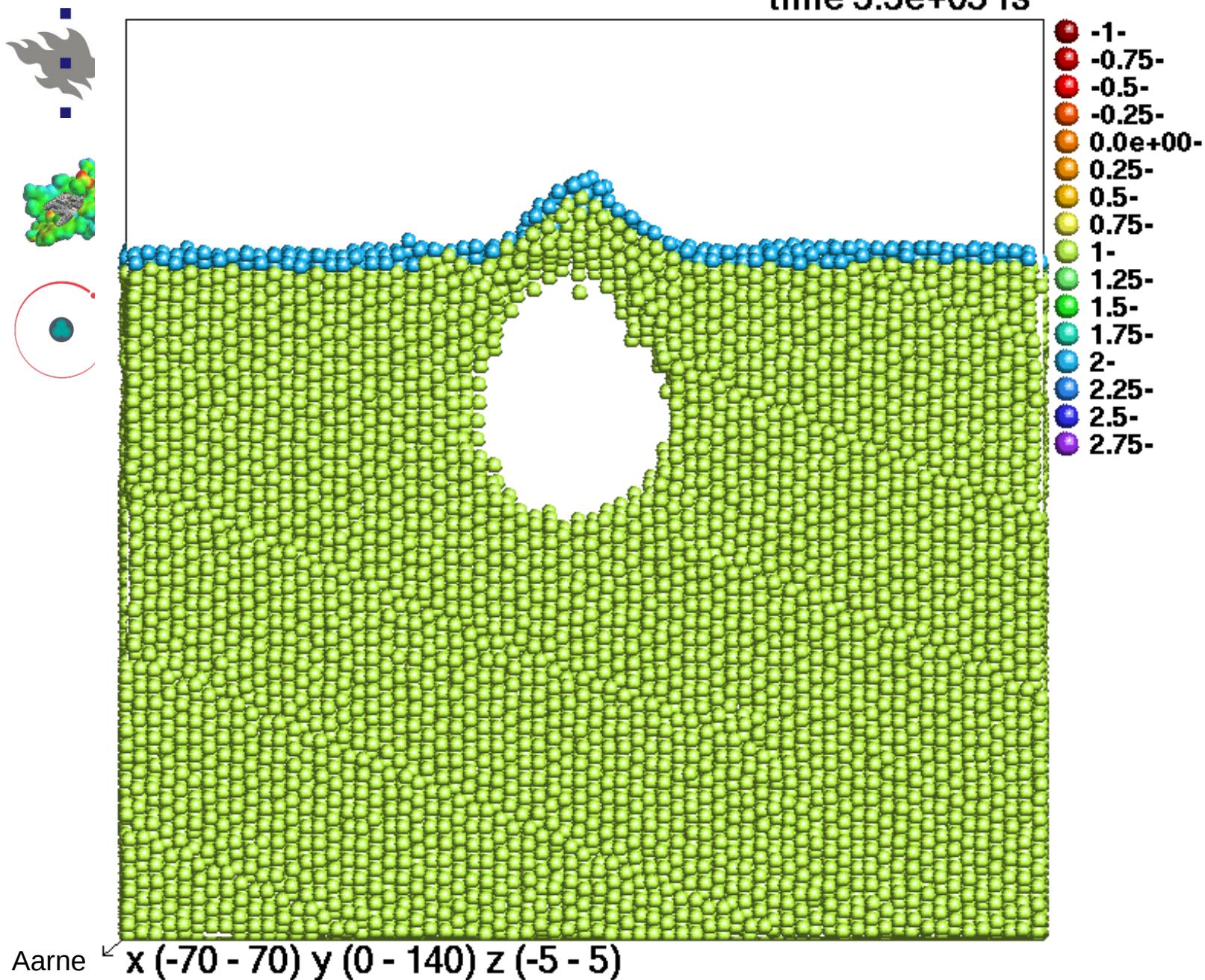
time 3.2e+05 fs



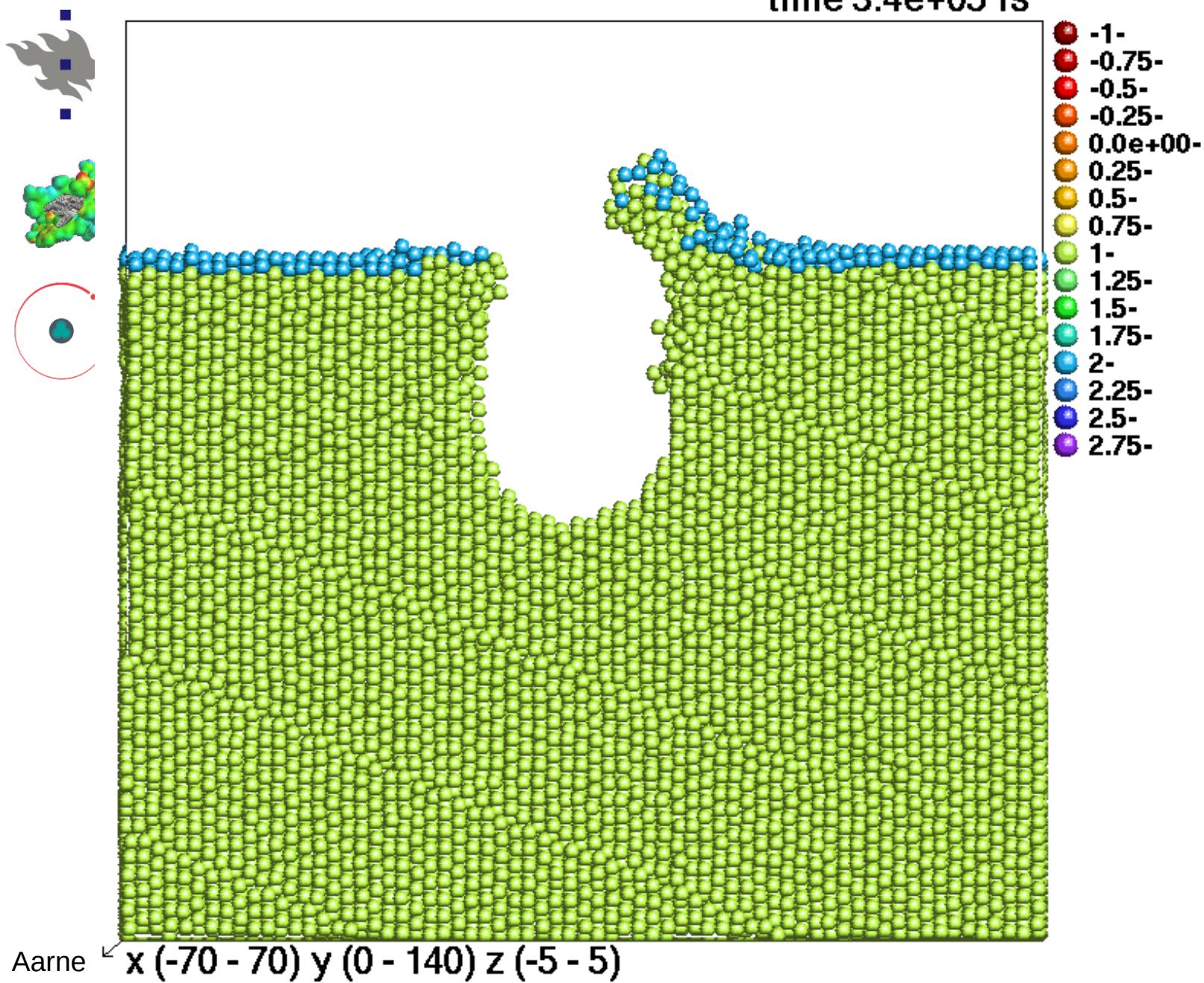
time 3.25e+05 fs



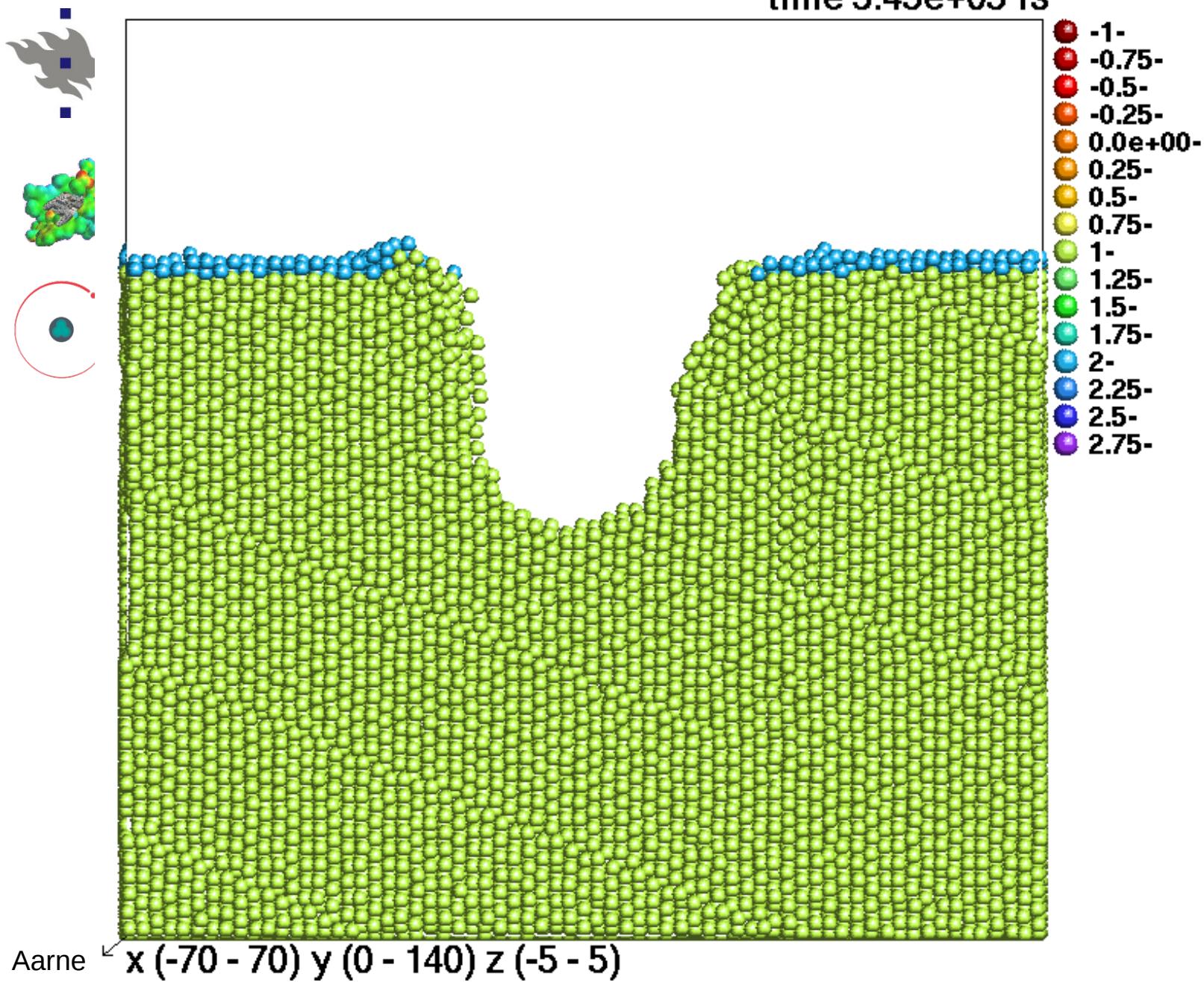
time 3.3e+05 fs

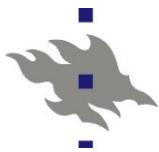


time 3.4e+05 fs

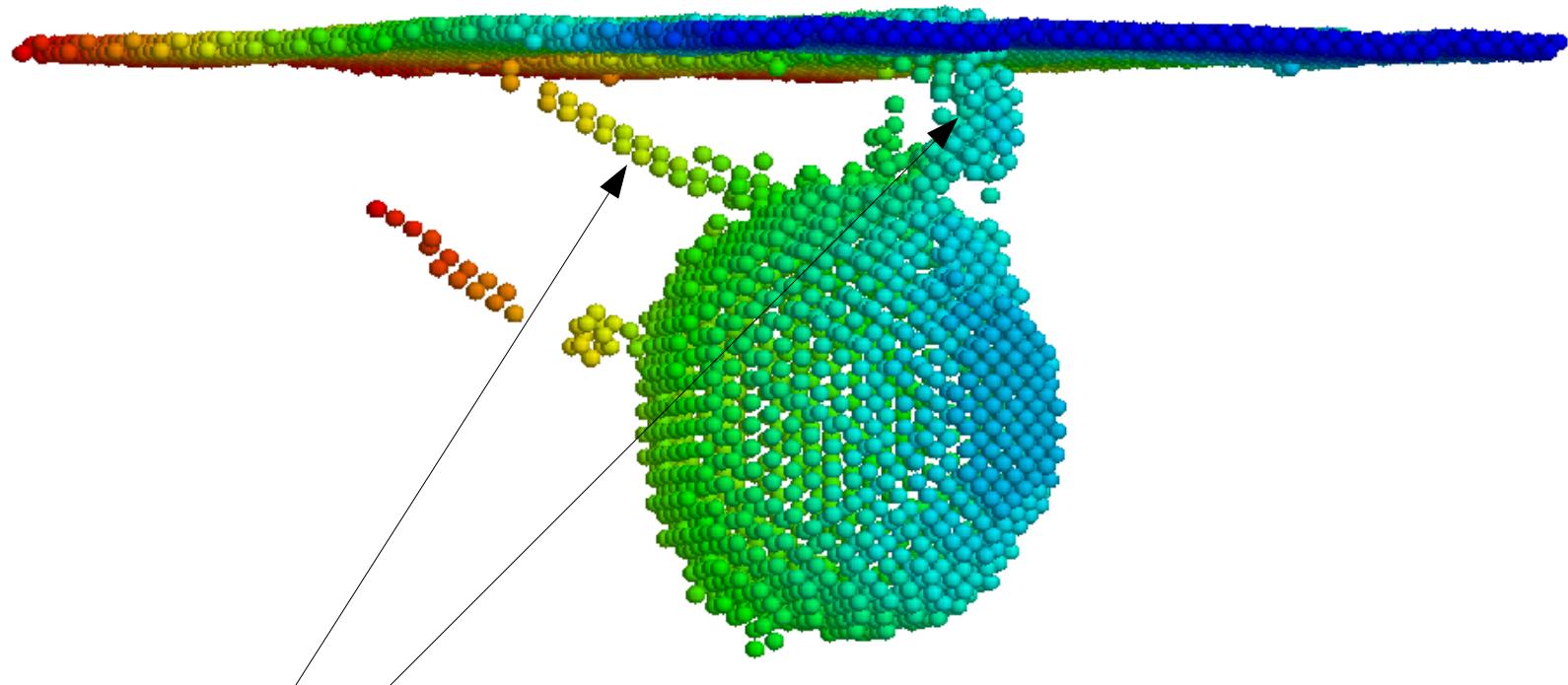


time 3.45e+05 fs





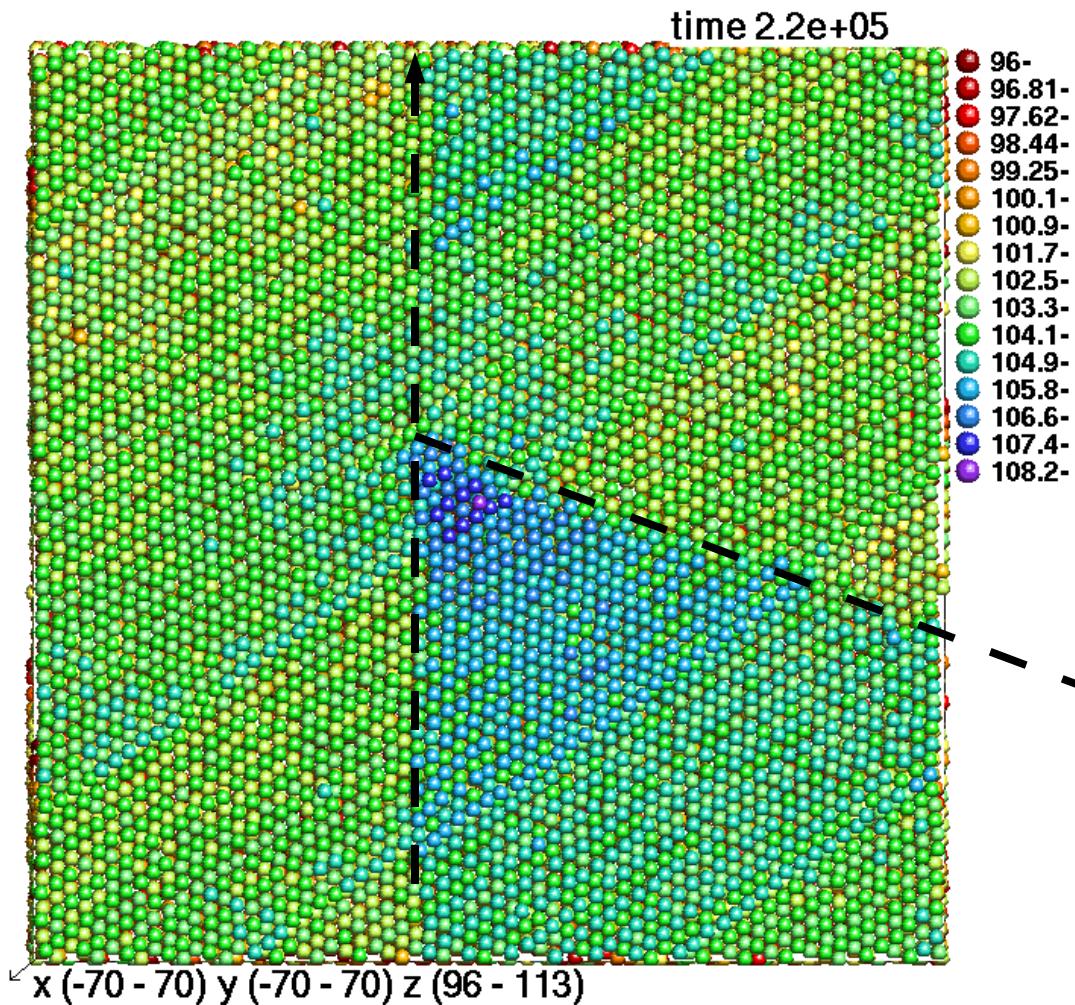
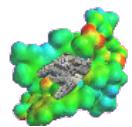
Simulations



Dislocation lines



Simulations



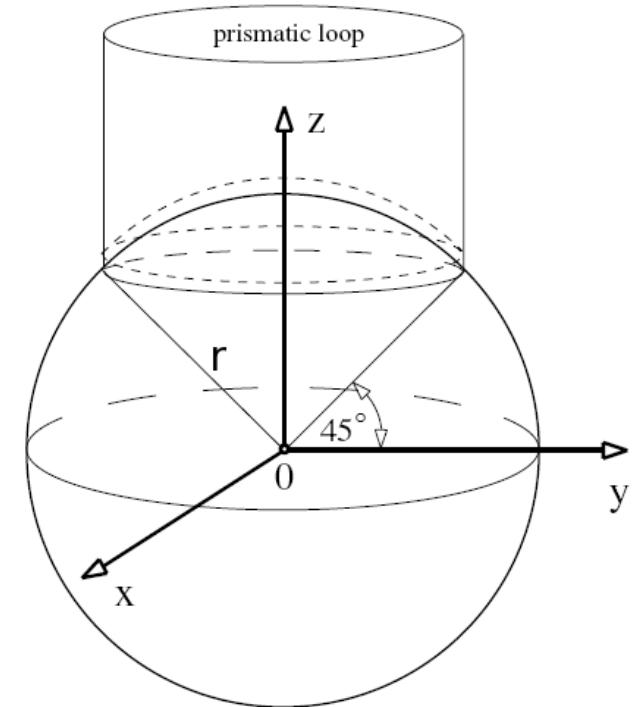
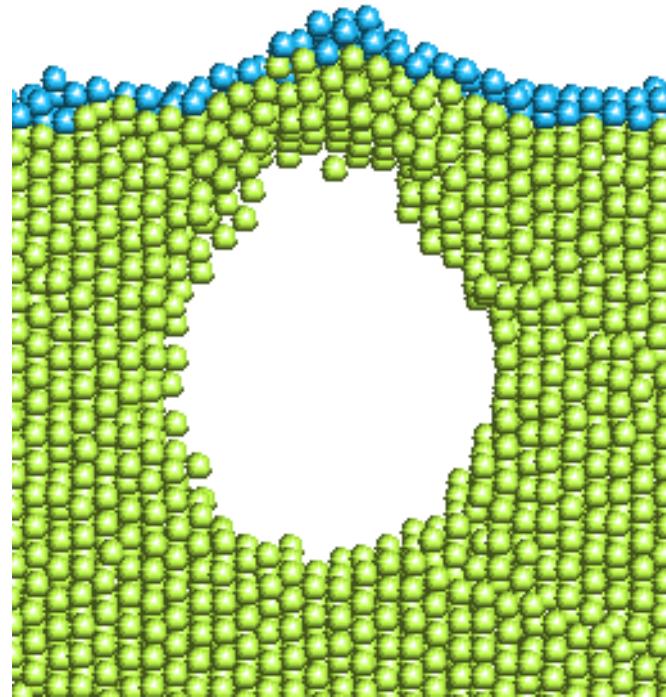
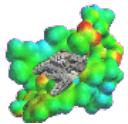
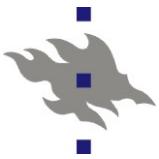
$$\vec{a} = (1, 1, -2)$$
$$\vec{b} = (1, 1, 2)$$

$$\cos \varphi(\vec{a}, \vec{b}) = \frac{\vec{a} \cdot \vec{b}}{|\vec{a}| |\vec{b}|}$$

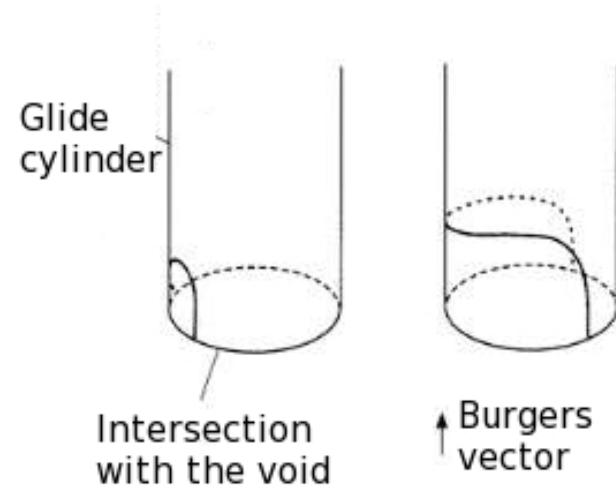
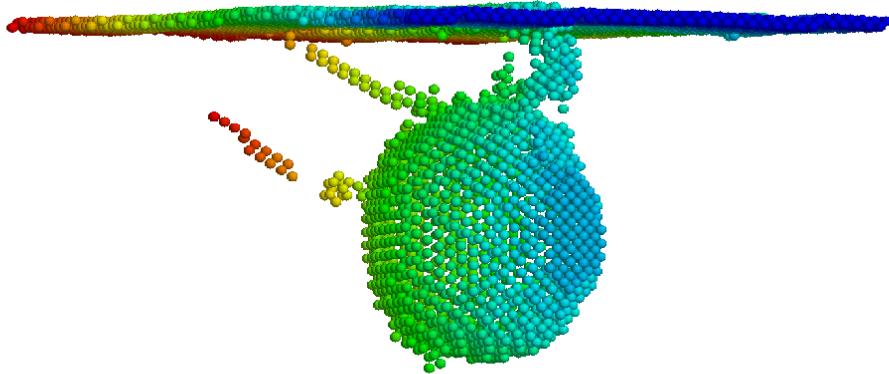
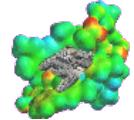
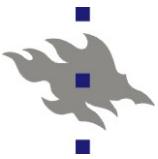
$$\varphi(\vec{a}, \vec{b}) = 109,47^\circ$$

$$180^\circ - 109,27^\circ = 70,73^\circ$$

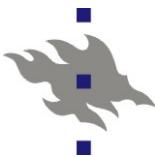
as observed in this image



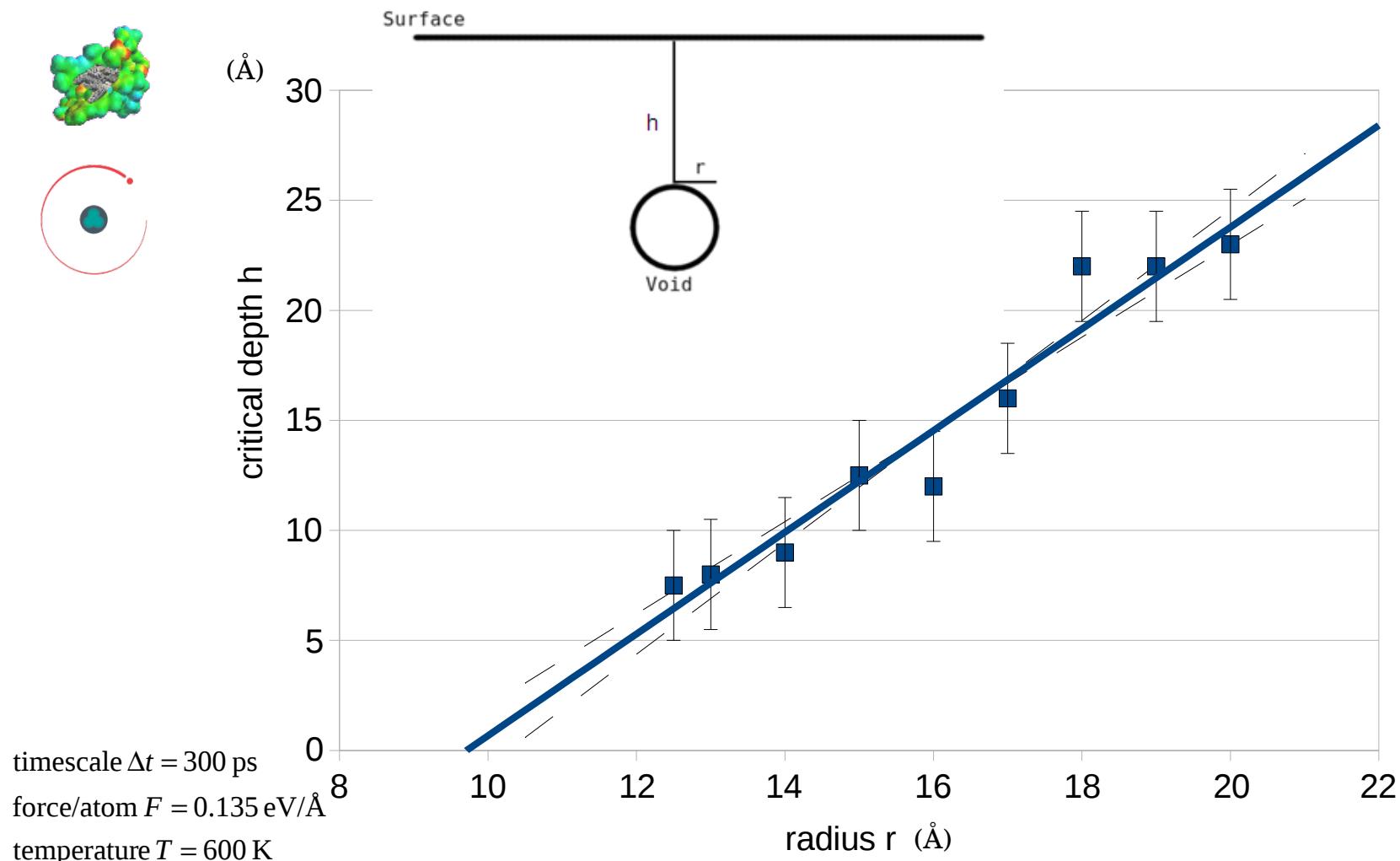
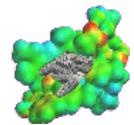
Void Growth by Dislocation Emission,
Lubarda, Schneider, Kalantar,
Remington, Meyers, 2004

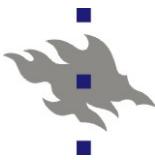


Introduction to Dislocations, Hull, Bacon, 2001

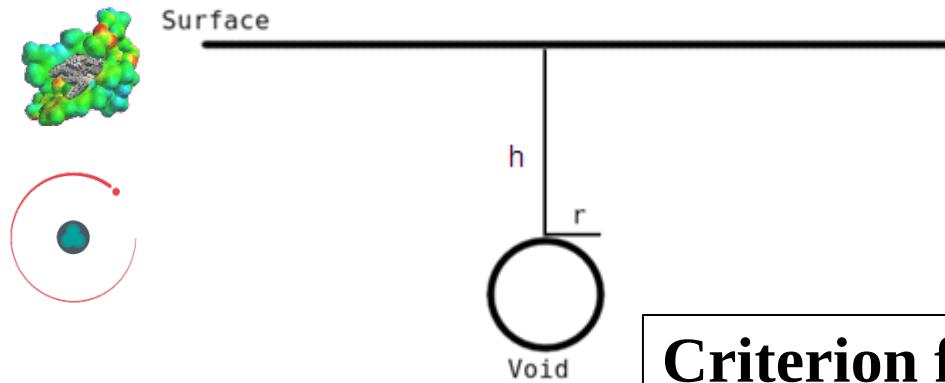


Simulations





Criterion for growth



timescale $\Delta t = 300 \text{ ps}$

force/atom $F = 0.135 \text{ eV}/\text{\AA}$

temperature $T = 600 \text{ K}$



$$a = 2.31 \pm 0.22$$

$$r_{\min} = (9.71 \pm 3.5) \text{ \AA}$$

Criterion for growth

Growth will occur during timescale Δt if

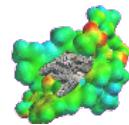
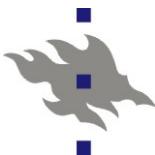
$$h < a(r - r_{\min})$$

where

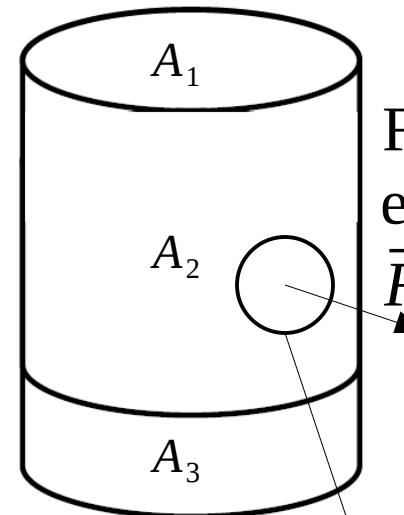
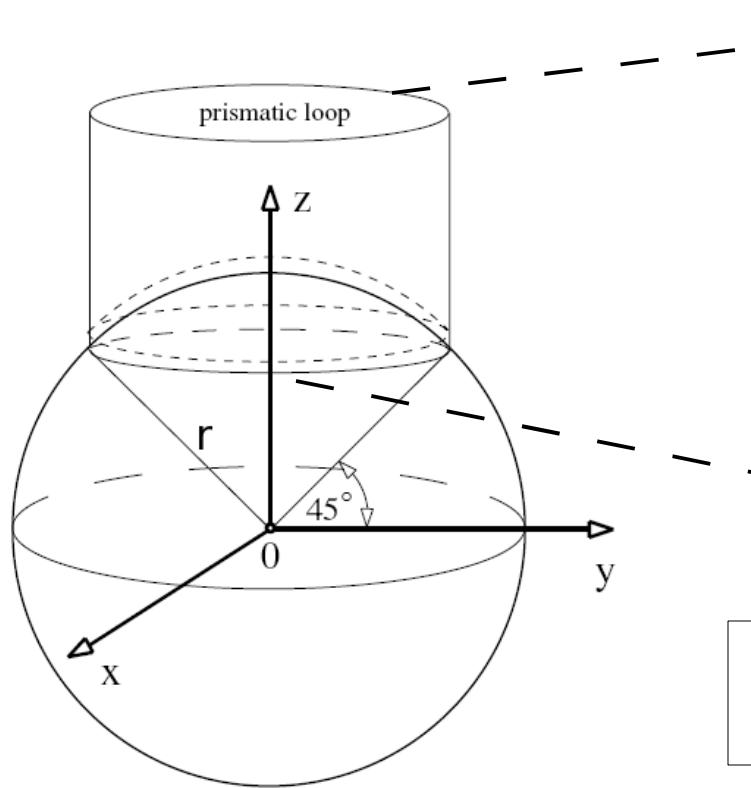
h is the depth of the void

r is the radius of the void

r_{\min} is the minimum radius for the growth to occur



Criterion for growth



Force on surface element

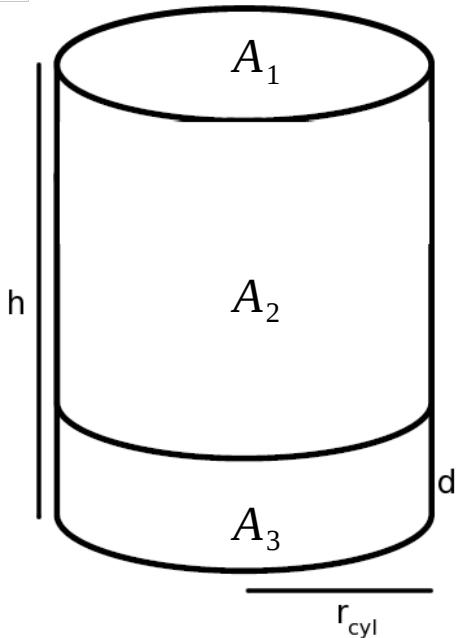
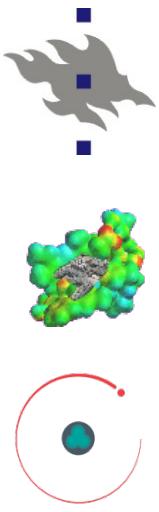
$$\vec{F}$$

Surface element with area $\Delta\sigma$ and direction \vec{v}

Void Growth by Dislocation Emission,
Lubarda, Schneider, Kalantar,
Remington, Meyers, 2004

$$\text{Stress vector } \vec{T}^{\vec{v}} := \lim_{\Delta\sigma \rightarrow 0} \frac{\vec{F}}{\Delta\sigma}$$

Mathematical Theory of Elasticity, Sokolnikoff, 1956



In equilibrium

$$\int_{surface} \vec{T}_y^{\vec{v}} = 0$$

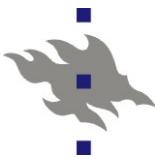
$$\int_{A_1} \vec{T}_y^{\vec{v}} + \int_{A_2} \vec{T}_y^{\vec{v}} + \int_{A_3} \vec{T}_y^{\vec{v}} = 0$$

$$\langle \vec{T}_y^{\vec{v}} \rangle_{A_1} \pi r_{cyl}^2 + \underbrace{\langle \vec{T}_y^{\vec{v}} \rangle_{A_2} 2 \pi r_{cyl} (h - d)}_{B_{T,2}} + \underbrace{\langle \vec{T}_y^{\vec{v}} \rangle_{A_3} 2 \pi r_{cyl} d}_{B_{T,3}} = 0$$

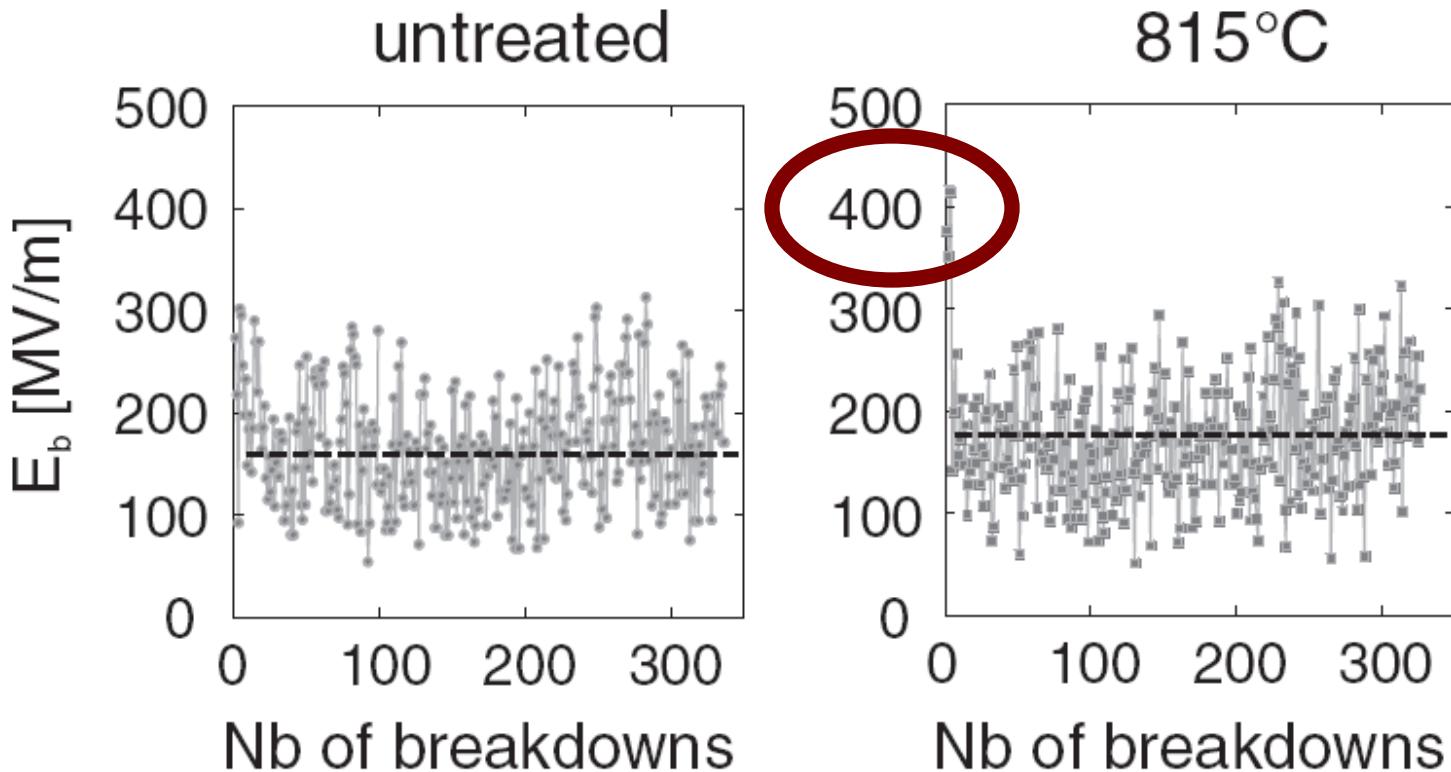
$$h < h_{max} = -\frac{\langle \vec{T}_y^{\vec{v}} \rangle_{A_1}}{2^{3/2} B_{T,2}} \left(r - \frac{2^{3/2} (B_{T,2} - B_{T,3})}{\langle \vec{T}_y^{\vec{v}} \rangle_{A_1}} d \right)$$



Criterion for growth
 $h < a(r - r_0)$



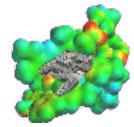
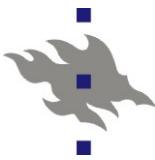
Effect of heat treatment



DC Breakdown Conditioning and Breakdown Rate of Metals and Metallic Alloys under Ultrahigh Vacuum,
Descouedres, Ramsvik, Calatroni, Taborelli, Wuensch, 2009

Effect of 815°C heat treatment on Cu.

Voids would be annealed out in high temperatures...



Conclusions

Voids in copper

- Voids have been observed in the structures
- Kirkendall effect may create near-surface voids

Dislocation emission from voids is possible

- Forces used in simulation are huge
- Need to do further analysis

Criterion for growth

Growth will occur during timescale Δt if

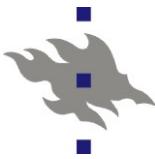
$$h < a(r - r_{\min})$$

where

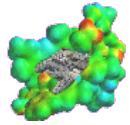
h is the depth of the void

r is the radius of the void

r_{\min} is the minimum radius for the growth to occur



Discussion



- Dislocations are probably nucleated easier from a grain boundary void
- Dislocation emission from the void might initiate a growth on surface that would enhance the field
- Dislocation emission might lead to a detachment of a particle from the surface
 - > Particle detachment from anode might create impact crater on cathode where the field would be enhanced